

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



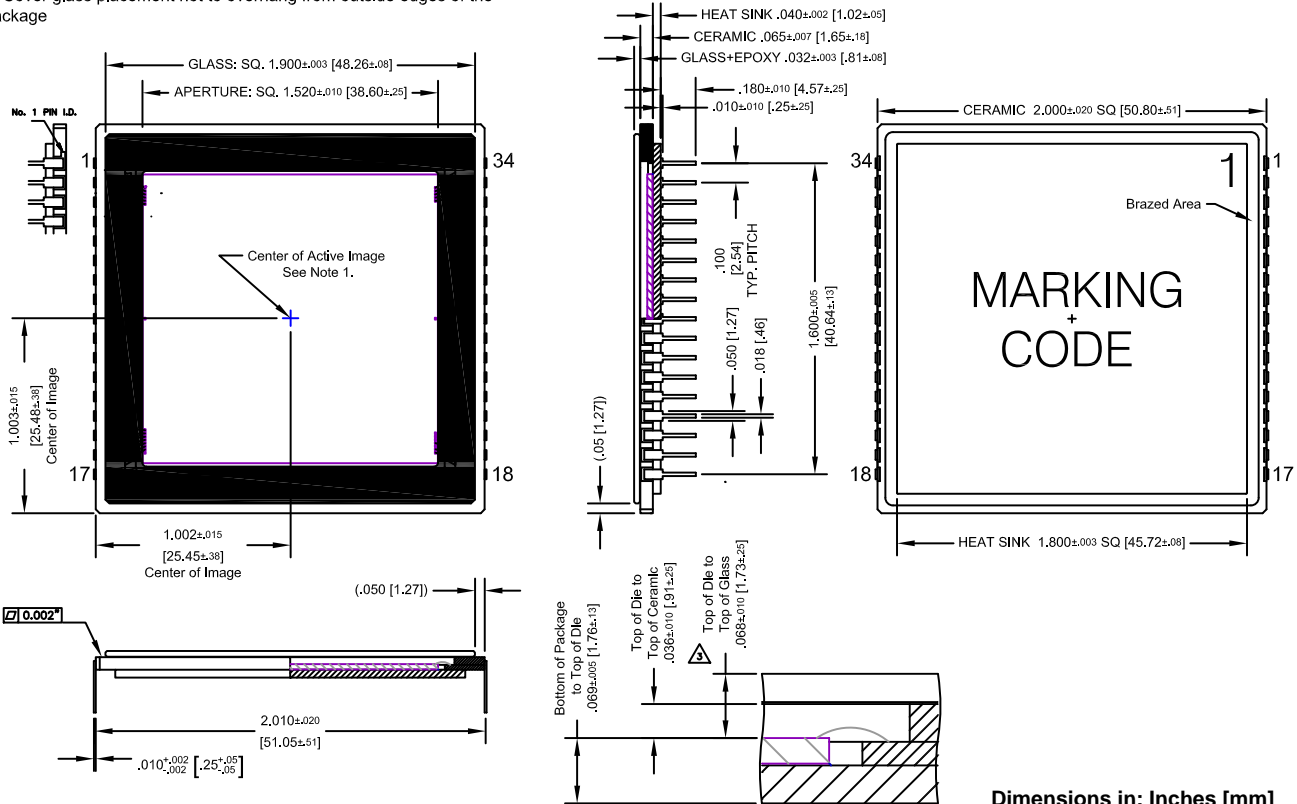
CERAMIC DIP 34, 50.8x50.8 CASE 125BK ISSUE O

DATE 03 JUL 2014

NOTES:

- Center of Active Image is at (+.046, +.078)mm with respect to Center of Package at (0,0).
- Die is visually aligned within 1 degree of any package cavity edge.
- Cover glass placement not to overhang from outside edges of the package

SHOWN WITH SEALED COVER GLASS

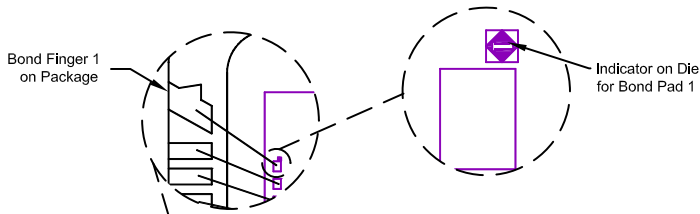


Dimensions in: Inches [mm]

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STATUS:	ON SEMICONDUCTOR STANDARD	
REFERENCE:		
DESCRIPTION:	CERAMIC DIP 34, 50.8x50.8	PAGE 1 OF 3

CERAMIC DIP 34, 50.8x50.8
CASE 125BK
ISSUE O

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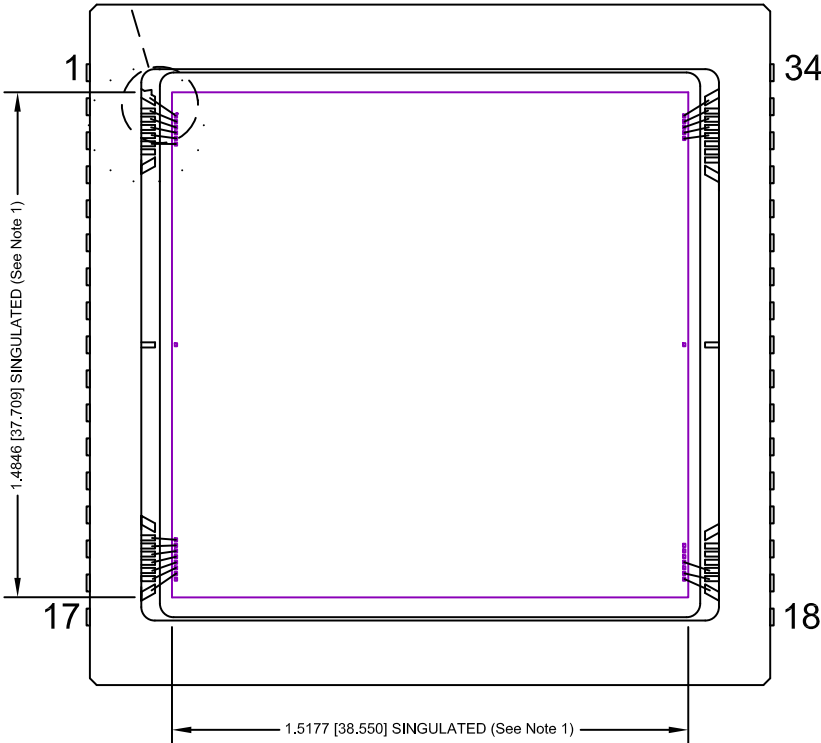


NOTES:

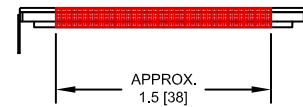
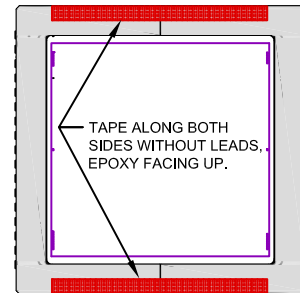
1. SINGULATION ASSUMES 50 MICRON KERF.
 STEPPED DIE DIMENSION ON WAFER FOR DICING
 PURPOSES IS 38.60 mm X 37.76 mm.

2. APPLY TAPE TO TWO SIDES AS SHOWN (ASSY # 20304846)

SHOWN WITH NO COVER GLASS



2. SHOWN WITH
 TAPED ON COVER GLASS



Dimensions in: Inches [mm]

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